

Application No. 09/909,934

Filed: July 20, 2001

TC Art Unit: 2827

Confirmation No.: 2402

AMENDMENT TO THE SPECIFICATION

Please amend the paragraph beginning on page 5, line 20 to read as follows:

The lead frame (10) is preferably of a metallic foil base, like copper or other suitable materials. The metallic foil is either etched or stamped to form the lead frame (10) that contain a plurality of integrated circuits (11). Each of the integrated circuit (11) has a die pad (not shown) for attaching a die and a plurality of leads (not shown) projecting away from the die pads. The lead frame (10) is surrounded by a peripheral pad (14) that is an inactive part of the metallic foil. The peripheral pad (14) is provided with a plurality of stress-relief means ~~(15)~~ and a plurality of interlocking means ~~(16)~~ in the form of holes and slots. Extensive research and experimentation has revealed that for best result, at least three rows of stress-relief means ~~(15)~~, a first row (15), a second row (17), and a third row (18), and a row of interlocking means (16) are needed. The first and the third row of the stress-relief means (15 and 18 respectively) are provided with slots, while the second row (17) is provided with holes, preferably square holes. The holes and slots are arranged side by side in equal intervals for equal expansion and compression distribution. For the interlocking means (16), a

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plurality of slots are arranged at equal intervals in between the second and the third row of the stress-relief means (1517 and 18 respectively).